

EC 536 Fall 2012

Week 12 Pages (plus lecture notes)

Lithography

p.151- p. 154, Fig. 7.3 - 7.4

p. 164 - 166 (top), Eqn. 7.16 - 7.19, Fig. 7.15, 7.17, Table 7.4

Plasma

p.249-254 (No equations required in these pages), Fig. 10.14, 10.17, 10.20, 10.21,

Etching

p.258-261 top, Eqn.11.2 - 11.4, Fig. 11.1

Plasma Etching: p. 278, Fig. 11.17 top

Physical Vapor Deposition (PVD)

Evaporation: p. 295, Fig. 12.1, 12.6

Sputtering (No equations required in these pages),: p. 305 bottom- p. 306 top,
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Chemical Vapor Deposition (CVD)

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Atmospheric Pressure CVD (APCVD): p. 337 bottom - p. 338, Fig. 13.5

Low Pressure CVD (LPCVD): p339- p441 (top), Fig. 13.12 - 13.14

Plasma Enhanced CVD: p. 344